

METHOD OF FORMING CONDUCTOR WIRING PATTERN

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ABSTRACT OF THE DISCLOSURE

10 A method of forming a conductor wiring pattern
comprises: forming a first insulating layer on a surface
of a semiconductor wafer and also forming a second,
photosensitive insulating resin layer thereon; light-
exposing and developing the second insulating layer to
form pattern grooves so that the first insulating layer
is exposed at bottoms of the pattern grooves; forming a
15 plating seed layer on the second insulating layer
including inner surfaces of the pattern grooves and then
forming a resist pattern on the seed layer except for
portions of the pattern grooves; filling the pattern
grooves with a conductor by an electrolytic plating using
20 the seed layer as a power supply layer; and removing the
resist pattern and also removing the seed layer exposed
on the surface of the second insulating layer to form a
wiring pattern consisting of conductors remaining in the
pattern grooves.